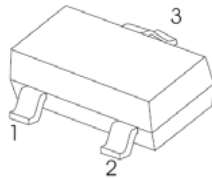


FEATURE

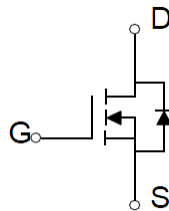
- High density cell design for low $R_{DS(ON)}$
- Voltage controlled small signal switch
- Rugged and reliable
- High saturation current capability

SOT-23

1. GATE
2. SOURCE
3. DRAIN

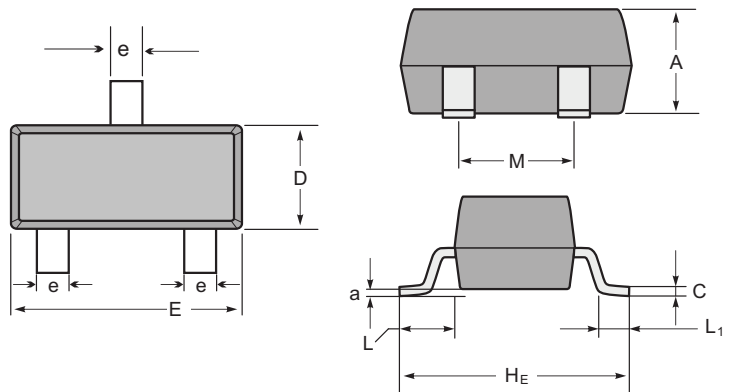


Equivalent circuit



Marking

Type number	Marking code
BSS123	SAW



SOT-23 mechanical data

UNIT		A	C	D	E	H _E	e	M	L	L ₁	a
mm	max	1.1	0.15	1.4	3.0	2.6	0.5	1.95	0.55 (ref)	0.36 (ref)	0.0
	min	0.9	0.08	1.2	2.8	2.2	0.3	1.7			0.15
mil	max	43	6	55	118	102	20	77	22 (ref)	14 (ref)	0.0
	min	35	3	47	110	87	12	67			6

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
N-MOSFET			
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current (note 1)	I_D	0.17	A
Pulsed Drain Current ($t_p=10\mu\text{s}$)	I_{DM}	0.68	A
Continuous Source-Drain Diode Current	I_S	0.17	A
Power Dissipation	P_D	0.35	W
Thermal Resistance from Junction to Ambient (note 1)	$R_{\theta JA}$	357	$^\circ\text{C/W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~+150	$^\circ\text{C}$
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	T_L	260	$^\circ\text{C}$

BSS123

$T_a=25^{\circ}\text{C}$ unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	100			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =100V, V _{GS} = 0V			1	μA
		V _{DS} =20V, V _{GS} = 0V			10	nA
Gate-body leakage current	I _{GSS}	V _{GS} =±20V, V _{DS} = 0V			±50	nA
Gate threshold voltage (note 2)	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1		2.8	V
Drain-source on-resistance(note 2)	R _{DS(on)}	V _{GS} =4.5V, I _D =0.17A			10	Ω
		V _{GS} =10V, I _D =0.17A			6	Ω
Forward tranconductance(note 2)	g _{FS}	V _{DS} =10V, I _D =170mA	80			mS
Diode forward voltage	V _{SD}	I _S =340mA, V _{GS} = 0V			1.3	V
DYNAMIC CHARACTERISTICS (note 4)						
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f =1MHz		29	60	pF
Output Capacitance	C _{oss}			10	15	pF
Reverse Transfer Capacitance	C _{rss}			2	6	pF
SWITCHING CHARACTERISTICS (note 3,4)						
Turn-on delay time	t _{d(on)}	V _{GS} =10V, V _{DD} =30V, I _D =2.8A, R _{GEN} =50 Ω			8	ns
Turn-on rise time	t _r				8	ns
Turn-off delay time	t _{d(off)}				13	ns
Turn-off fall time	t _f				16	ns
Total Gate Charge	Q _g	V _{DS} =10V, I _D =0.22A, V _{GS} =10V		1.4	2	nC
Gate-Source Charge	Q _{gs}			0.15	0.25	nC
Gate-Drain Charge	Q _{gd}			0.2	0.4	nC

Notes :

- 1.Surface mounted on FR4 board using the minimum recommended pad size.
2. Pulse Test : Pulse width=300 μ s, duty cycle $\leq$ 2%.
3. Switching characteristics are independent of operating junction temperature.
4. Granted by design, not subject to producing.

RATING AND CHARACTERISTIC CURVES (BSS123)

